



#### N-CHANNEL ENHANCEMENT MODE MOSFET PLUS PNP TRANSISTOR

#### **Features**

- N-Channel MOSFET and PNP Transistor in One Package
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.0V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Ultra-Small Surface Mount Package
- Lead, Halogen and Antimony Free, RoHS Compliant (Note 2)
- ESD Protected MOSFET Gate up to 2kV
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Alloy 42 lead frame.
  Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 5
- Ordering Information: See Page 5
- Weight: 0.006 grams (approximate)

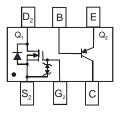
SOT-363







TOP VIEW



TOP VIEW

Internal Schematic

#### Maximum Ratings – MOSFET, Q1 @TA = 25°C unless otherwise specified

Charact	eristic	Symbol	Value	Units
Drain-Source Voltage		$V_{DSS}$	50	V
Gate-Source Voltage		$V_{GSS}$	±12	V
Drain Current (Note 1)	Continuous	I <sub>D</sub>	160	mA
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	560	mA

# Maximum Ratings - PNP Transistor, Q2 @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-50	V
Collector-Emitter Voltage	$V_{\sf CEO}$	-45	V
Emitter-Base Voltage	$V_{EBO}$	-5.0	V
Collector Current	lc	-100	mA

#### Thermal Characteristics, Total Device @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 2. No purposefully added lead. Halogen and Antimony Free.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead\_free/index.php.



# Electrical Characteristics - MOSFET @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 2)	-					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	50	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	10	μΑ	$V_{DS} = 50V$ , $V_{GS} = 0V$
Gate-Body Leakage	I <sub>GSS</sub>	_	_	1.0 5.0	μА	$V_{GS} = \pm 8V, V_{DS} = 0V$ $V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 2)						
Gate Threshold Voltage	$V_{GS(th)}$	0.7	0.8	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain-Source On-Resistance		_	3.1	4	Ω	$V_{GS} = 4V, I_{D} = 100mA$
Static Drain-Source On-Resistance	R <sub>DS</sub> (ON)	_	4	5	2.2	$V_{GS} = 2.5V, I_D = 80mA$
Forward Transconductance	9FS	180	_	_	mS	$V_{DS} = 10V, I_D = 100mA,$ f = 1.0KHz
DYNAMIC CHARACTERISTICS						•
Input Capacitance	C <sub>iss</sub>	_	25	_	pF	101/1/
Output Capacitance	Coss		5		pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	_	2.1	_	pF	TI = 1.0IVII IZ

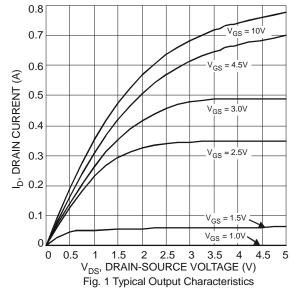
## Electrical Characteristics - PNP Transistor @TA = 25°C unless otherwise specified

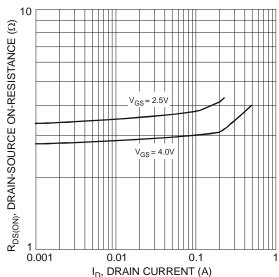
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage (Note 4)	V <sub>(BR)CBO</sub>	-50	_		V	$I_C = 10\mu A, I_B = 0$
Collector-Emitter Breakdown Voltage (Note 4)	V <sub>(BR)CEO</sub>	-45	_	—	V	$I_C = 10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage (Note 4)	V <sub>(BR)EBO</sub>	-5	_		V	$I_E = 1 \mu A, I_C = 0$
DC Current Gain (Note 4)	h <sub>FE</sub>	220	290	475	_	$V_{CE} = -5.0V$ , $I_{C} = -2.0mA$
Collector-Emitter Saturation Voltage (Note 4)	V <sub>CE(SAT)</sub>		_	-100	mV	$I_C = -10mA$ , $I_B = -0.5mA$
Concetor Emitter Cataration Voltage (Note 4)	VCE(SAT)			-400	1110	$I_C = -100 \text{mA}, I_B = -5.0 \text{mA}$
Base-Emitter Saturation Voltage (Note 4)	V <sub>BE(SAT)</sub>	_	-700	_	mV	$I_C = -10 \text{mA}, I_B = -0.5 \text{mA}$
Date Elimiter Gataration Voltage (1916-1)	V BE(SAT)	_	-900	_		$I_C = -100 \text{mA}, I_B = -5.0 \text{mA}$
Base-Emitter Voltage (Note 4)	V <sub>BE(ON)</sub>	-600	_	-750	mV	$V_{CE} = -5.0V, I_{C} = -2.0mA$
Dase Emilier Voltage (Note 4)	V BE(ON)	_	_	-820	111 V	$V_{CE} = -5.0V, I_{C} = -10mA$
Collector-Cutoff Current (Note 4)	lone	_	_	-15	nA	$V_{CB} = -30V$
Collector-Cutoff Current (Note 4)	I <sub>CBO</sub>	_	_	-4.0	μA	$V_{CB} = -30V, T_A = 150^{\circ}C$
Collector-Emitter Cut-Off Current (Note 4)	I <sub>CES</sub>	_	_	-100	nA	$V_{CE} = -45V$
Gain Bandwidth Product	f <sub>T</sub>	100		_	MHz	$V_{CE} = -5.0V$ , $I_{C} = -10mA$ , $f = 100MHz$
Output Capacitance	C <sub>OB</sub>		_	4.5	pF	V <sub>CB</sub> = -10V, f = 1.0MHz
Noise Figure	NF	_		10	dB	$I_C = -0.2 \text{mA}, V_{CE} = -5.0 \text{Vdc},$
ivoise rigure	INF	_		10	ub	$R_S = 2.0K\Omega$ , $f = 1.0KHz$ , $BW = 200Hz$

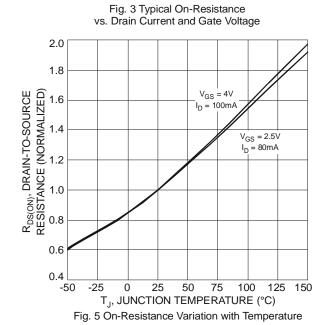
Notes: 4. Short duration pulse test used to minimize self-heating effect.

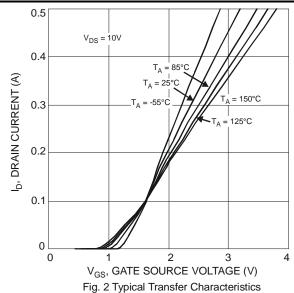


### **MOSFET**









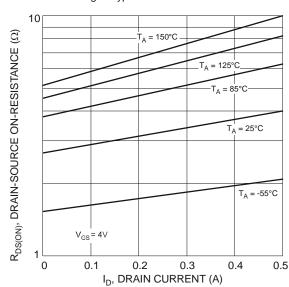
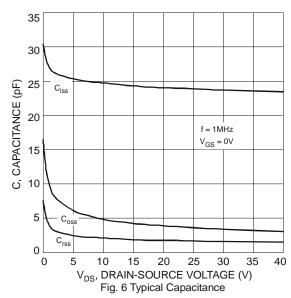


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature





# **MOSFET** (continued)

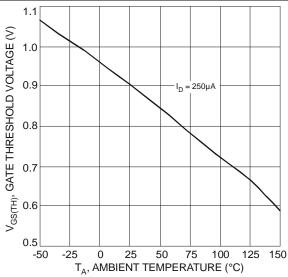


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

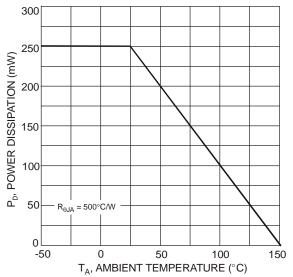


Fig. 9 Derating Curve - Total Package Power Dissipation

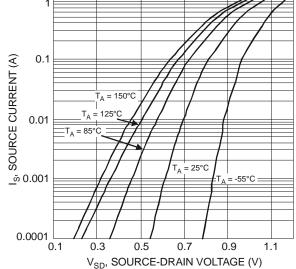
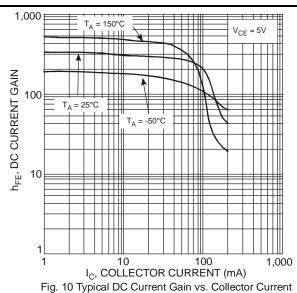


Fig. 8 Diode Forward Voltage vs. Current



## **PNP Transistor**



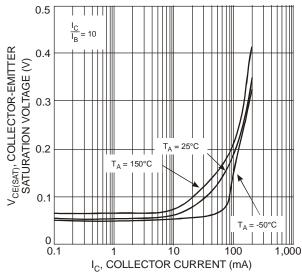


Fig. 11 Collector-Emitter Saturation Voltage vs. Collector Current

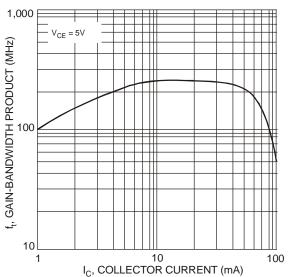


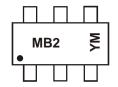
Fig. 12 Typical Gain-Bandwidth Product vs. Collector Current

### Ordering Information (Note 5)

- 1			
	Part Number	Case	Packaging
	DMB54D0UDW-7	SOT-363	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



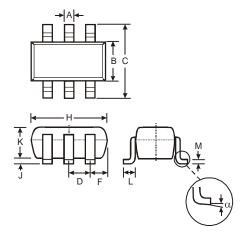
MB2 = Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key

Year	2008		2009	2010		2011	2012		2013	2014		2015
Code	V		W	X		Υ	Z		Α	В		С
Manth												
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	/ Dec

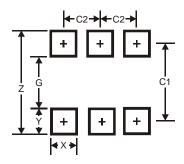


# **Package Outline Dimensions**



SOT-363						
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
С	2.00	2.20				
D	0.65	Тур				
F	0.40	0.45				
Н	1.80	2.20				
J	0	0.10				
K	0.90	1.00				
L	0.25	0.40				
М	0.10	0.22				
α	0°	8°				
All Di	mensions	in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65



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